



### General Description

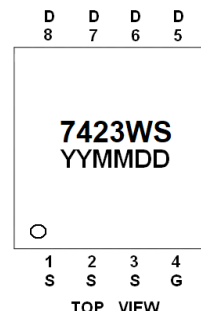
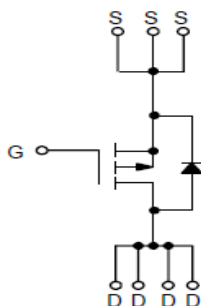
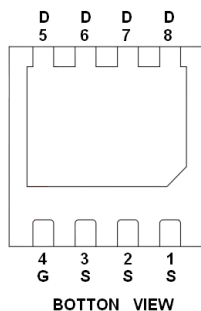
AFP7423WS, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

- -60V/-12A,  $R_{DS(ON)} = 25m\Omega @ V_{GS} = -10V$
- -60V/-10A,  $R_{DS(ON)} = 35m\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN3X3-8L package design

### Pin Description ( DFN3X3-8L )



### Application

- Load Switches
- Half-Bridge Motor Drives
- High Voltage Non-Synchronous Buck Converters

### Pin Define

Pin	Symbol	Description
1~3	S	Source
4	G	Gate
5~8	D	Drain

### Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP7423WSFN338RG	7423WS	DFN3X3-8L	Tape & Reel	5000 EA

※ YY year code

※ MM month code

※ DD date code

※ AFP7423WSFN338RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ Unless otherwise noted)

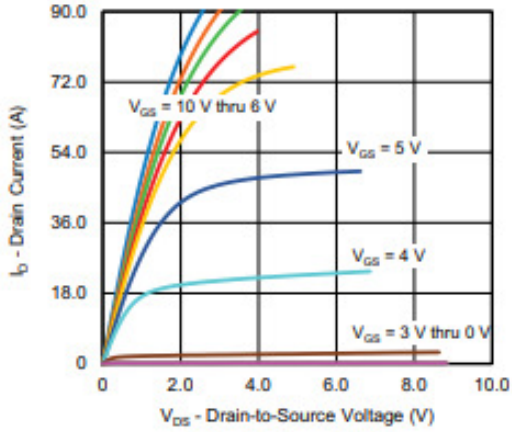
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DSS}$	-60	V
Gate -Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current ( $T_J=150^\circ\text{C}$ )	$I_D$	$T_C=25^\circ\text{C}$	30
		$T_C=70^\circ\text{C}$	24
		$T_A=25^\circ\text{C}$	-14
		$T_A=70^\circ\text{C}$	-10
Pulsed Drain Current	$I_{DM}$	-75	A
Continuous Source Current (Diode Conduction)	$I_S$	$T_C=25^\circ\text{C}$	-45
		$T_A=25^\circ\text{C}$	-4
Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$	4.8
		$T_A=70^\circ\text{C}$	3.0
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$t \leq 10\text{ s}$	$R_{\theta JA}$	26
Thermal Resistance-Junction to Case	Steady-State	$R_{\theta JC}$	2.2

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ Unless otherwise noted)

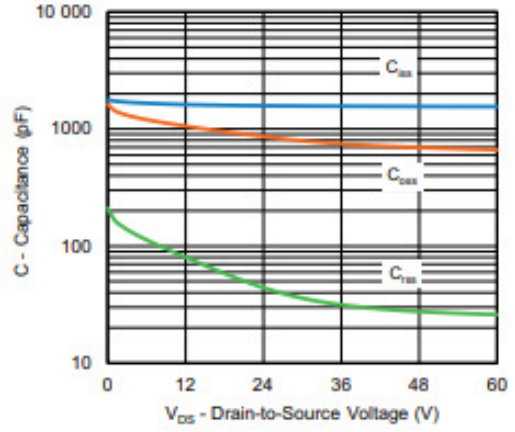
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D = -250\mu\text{A}$	-60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D = -250\mu\text{A}$	-1.0		-2.5	V
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -48V, V_{GS}=0V$			-1	uA
		$V_{DS} = -48V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			-20	
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -12A$		20	25	m $\Omega$
		$V_{GS} = -4.5V, I_D = -10A$		25	35	
Forward Transconductance	$g_{FS}$	$V_{DS} = -15V, I_D = -15A$		23		S
Gate resistance	$R_g$	$f=1\text{MHz}$	0.4	1.0	1.7	$\Omega$
Diode Forward Voltage	$V_{SD}$	$I_S = -5A, V_{GS}=0V$		-0.8	-1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=-30V, V_{GS}=-4.5V$ $I_D = -10.0A$		10	20	nC
Gate-Source Charge	$Q_{gs}$		7			
Gate-Drain Charge	$Q_{gd}$		3			
Input Capacitance	$C_{iss}$	$V_{DS}=-30V, V_{GS}=0V$ $f=1\text{MHz}$		1500		pF
Output Capacitance	$C_{oss}$		800			
Reverse Transfer Capacitance	$C_{rss}$		35			
Turn-On Time	$t_{d(on)}$	$V_{DD}=-30V, R_L=3.0\Omega$ $I_D = -10A, V_{GEN}=-10V$ $R_G=1.0\Omega$		15	30	ns
	$t_r$			5	10	
Turn-Off Time	$t_{d(off)}$			20	40	
	$t_f$			5	10	



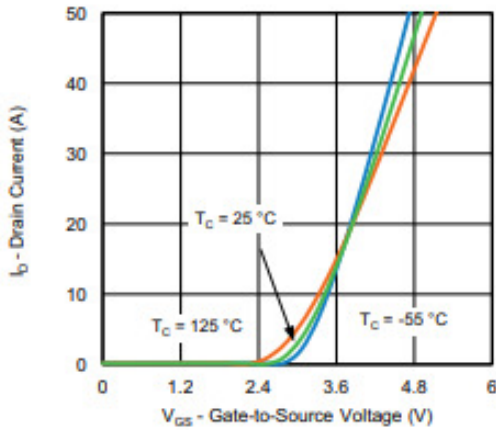
## Typical Characteristics



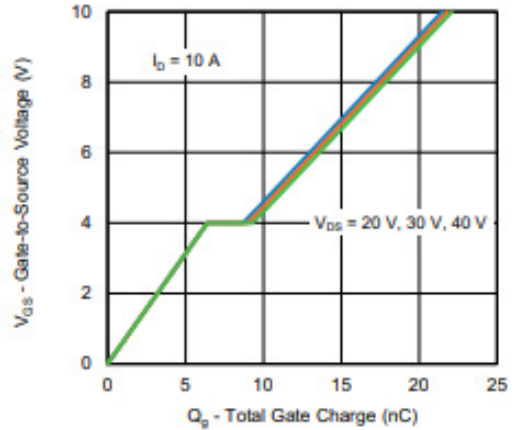
Output Characteristics



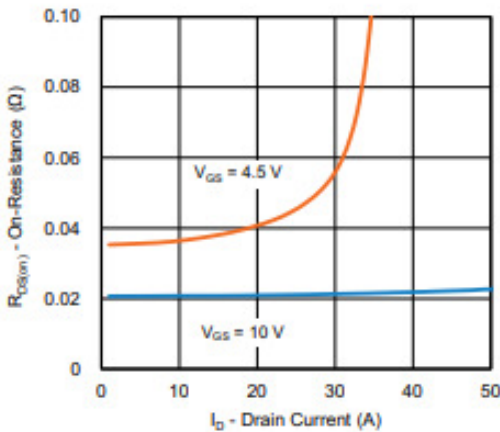
Transfer Characteristics



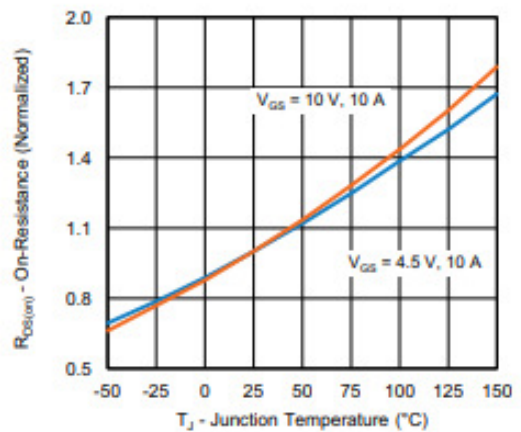
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



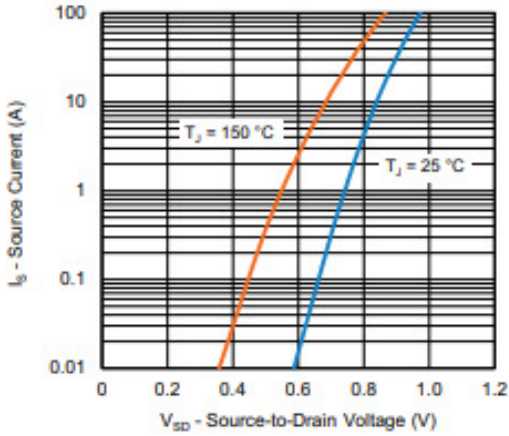
Gate Charge



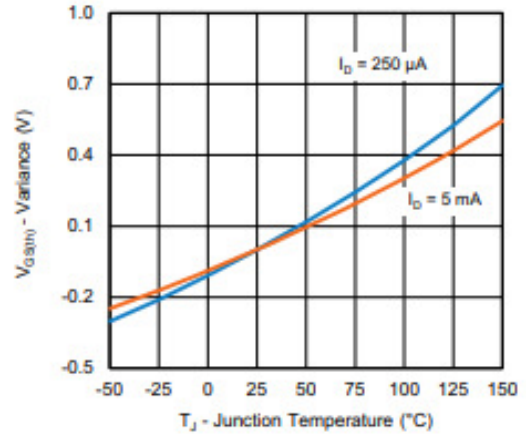
On-Resistance vs. Junction Temperature



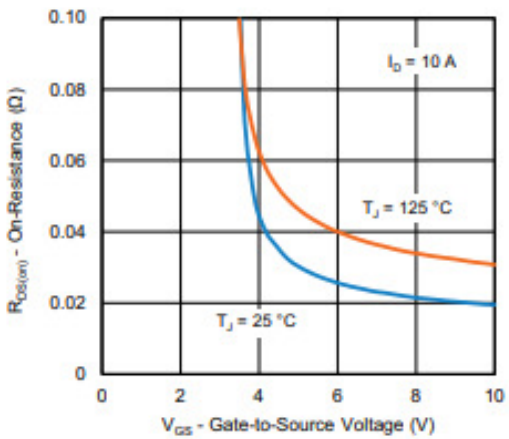
## Typical Characteristics



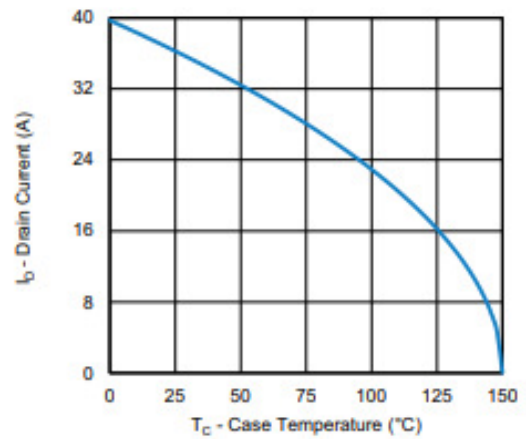
Source-Drain Diode Forward Voltage



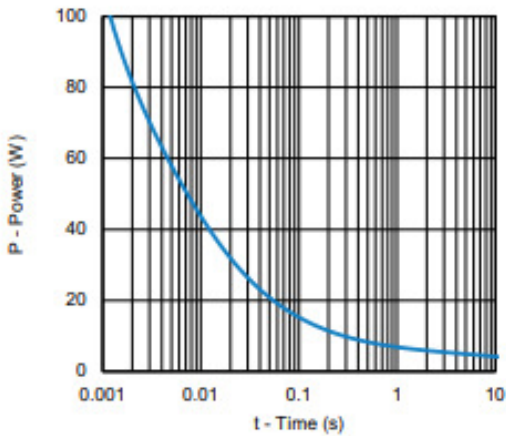
Threshold Voltage



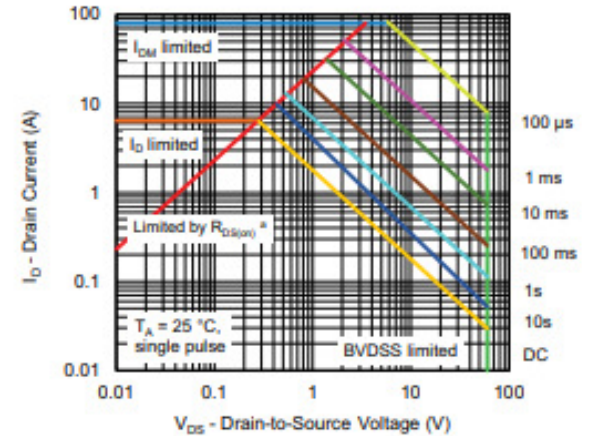
On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



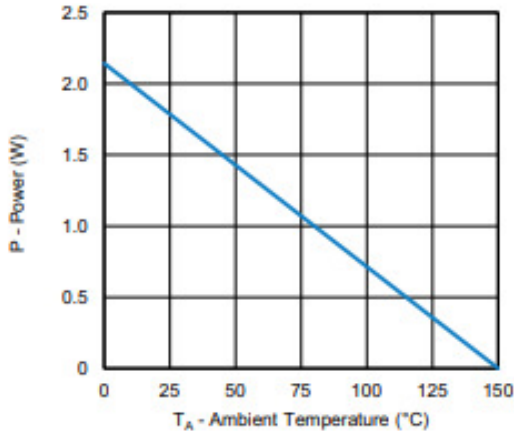
Current Derating <sup>a</sup>



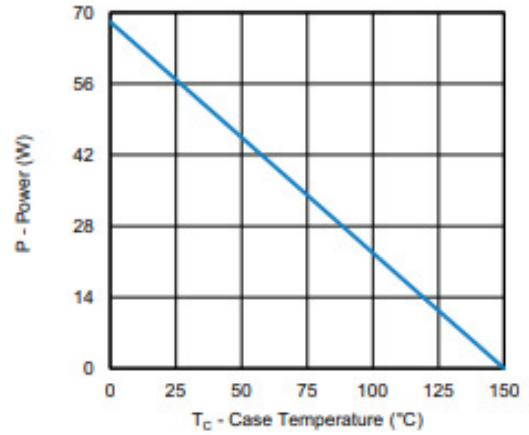
Safe Operating Area, Junction-to-Ambient



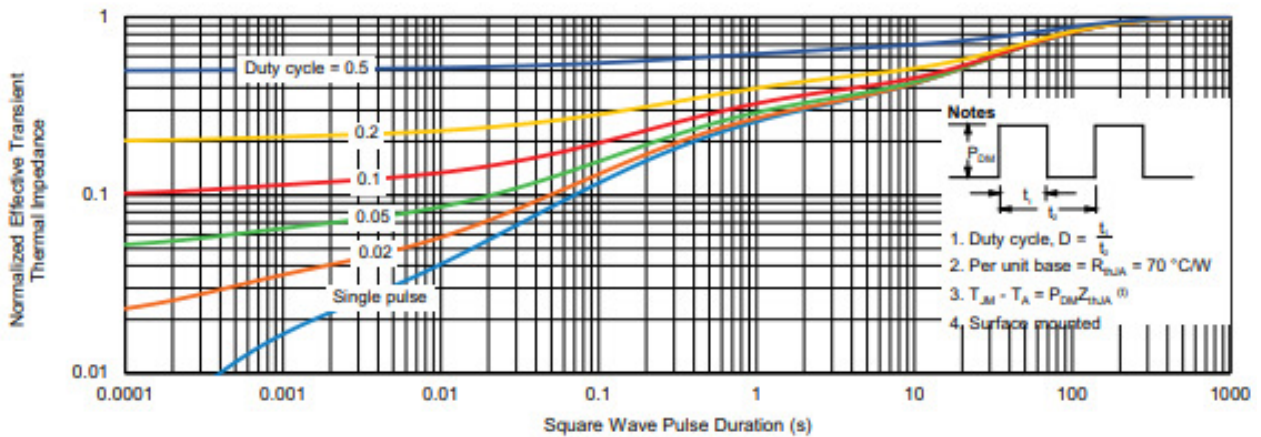
## Typical Characteristics



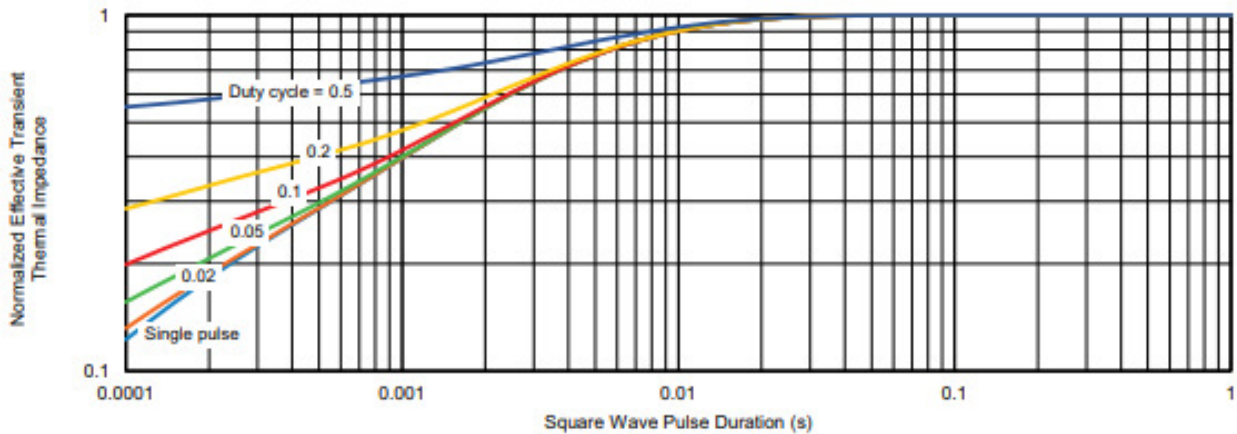
Single Pulse Power, Junction-to-Ambient



Power, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient



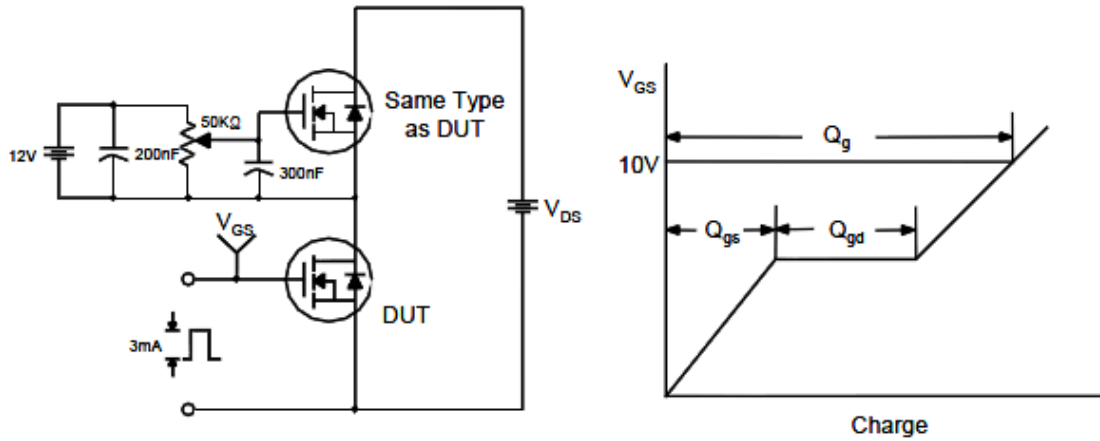
Normalized Thermal Transient Impedance, Junction-to-Case



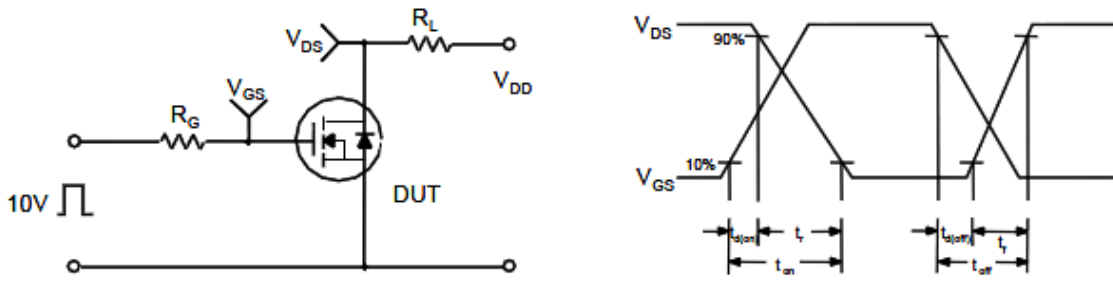


**Typical Characteristics**

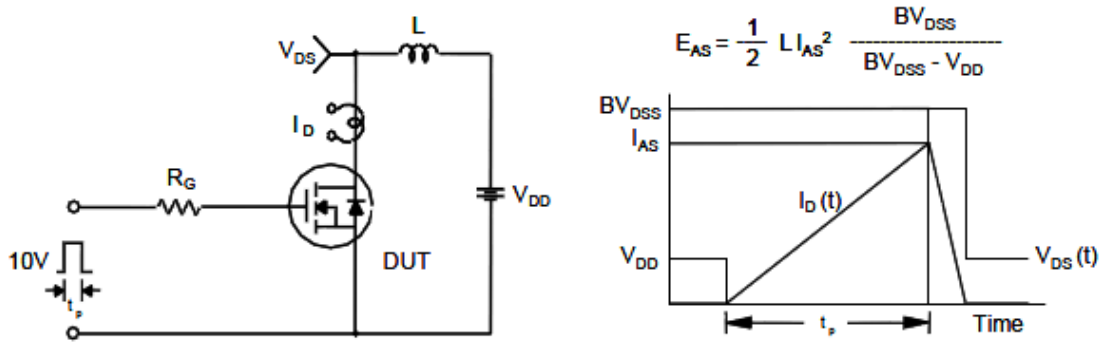
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

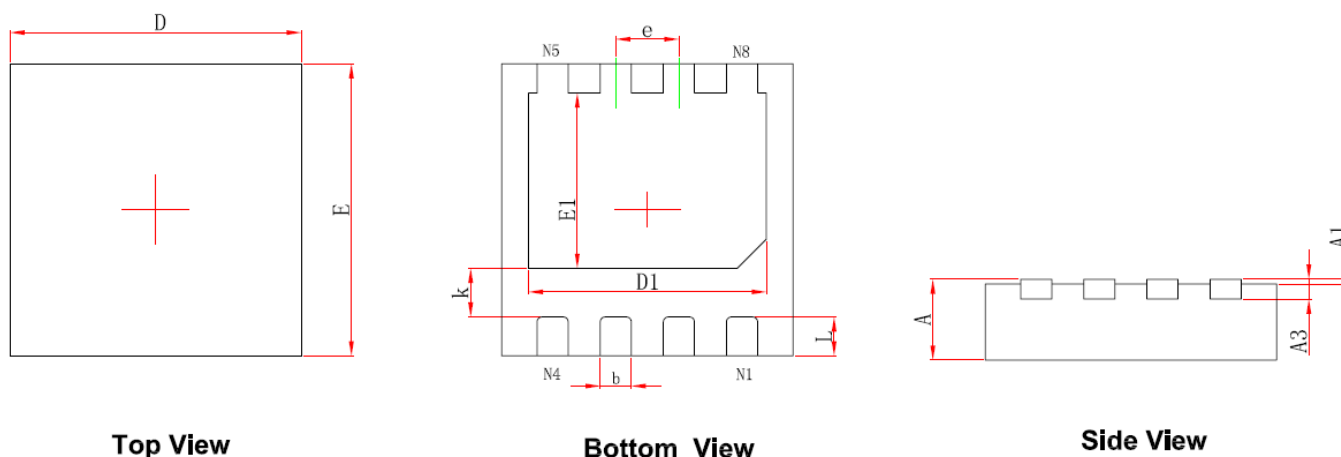


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( DFN3X3-8L )**



**Top View**

**Bottom View**

**Side View**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.800	0.900	0.031	0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.450	0.550	0.018	0.022
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019

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